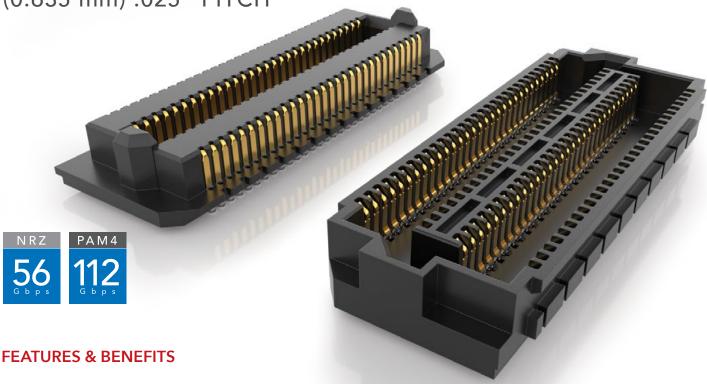


HIGH-PERFORMANCE ARRAY SYSTEM

(0.635 mm) .025 " PITCH



- Flexible open-pin-field and cost optimized, extreme performance solution
- Low-profile 5 mm stack height and up to 10 mm
- 0.635 mm pitch
- Four row design with up to 400 total pins; roadmap to 1,000+ pins
- Data rate capable of PCIe® 5.0 and 100 GbE
- In Development: Cable assembly designs,
 6, 8 and 10 rows, additional position counts



Solder ball technology for simplified processing



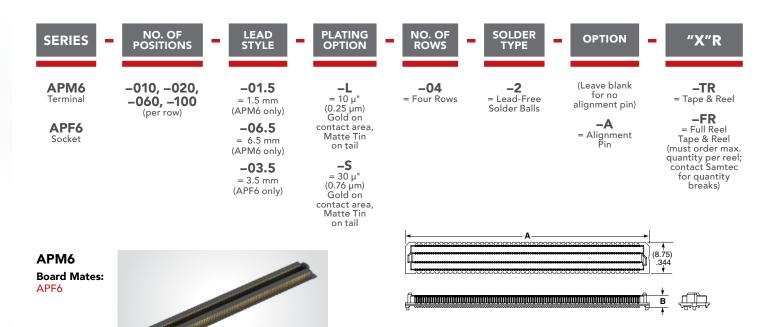
APF6 Sereis; 120 pins (actual size show)

KEY SPECIFICATIONS

STACK HEIGHTS	TOTAL PINS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	LEAD-FREE SOLDERABLE
5 mm - 10 mm	40 - 400	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	Yes



(0.635 mm) .025" PITCH • 112 Gbps PAM4 OPEN-PIN-FIELD ARRAYS



PRELIMINARY

NO. OF POSITIONS PER ROW	A
-010	(11.47) .451
-020	(17.82) .701
-060	(43.22) 1.701
-100	(68.62) 2.701

LEAD STYLE	В	
-01.5	(3.33) .131	
-06.5	(8.33) .328	

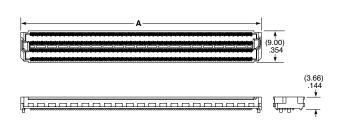
MATED HEIGHTS *					
APF6	APM6 LEAD STYLE				
LEAD STYLE	-01.5	-06.5			
-03.5	(5.00 mm) .197"	(10.00 mm) .394"			
* Processing conditions will affect mated height.					

APF6 Board Mates: APM6



PRELIMINARY

Notes: Some sizes, styles and options are non-standard, non-returnable



NO. OF POSITIONS PER ROW	Α
-010	(11.47) .451
-020	(17.82) .701
-060	(43.22) 1.701
-100	(68.62) 2.701